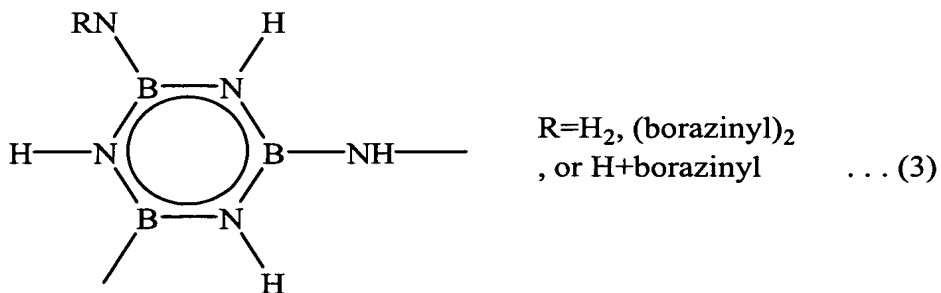
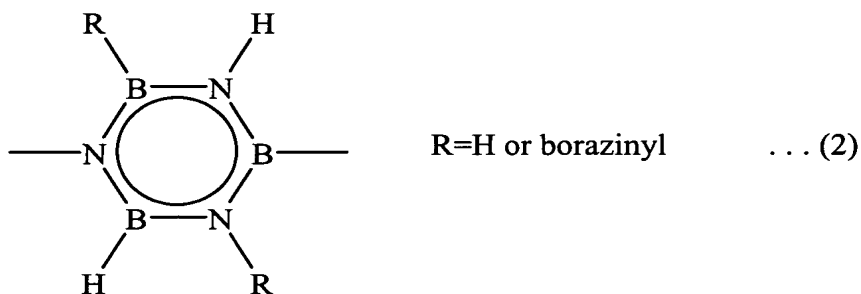
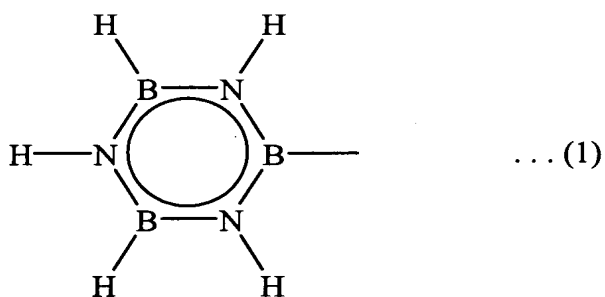


IN THE CLAIMS

Please amend the claims as follows:

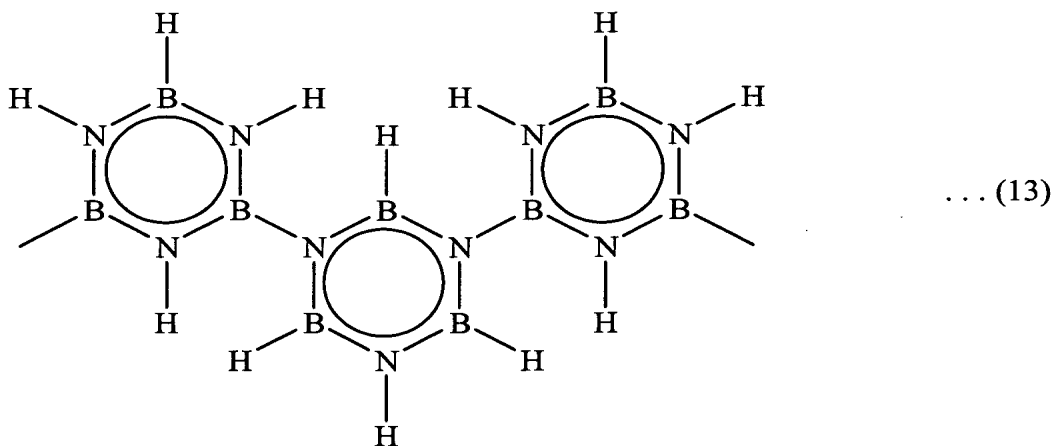
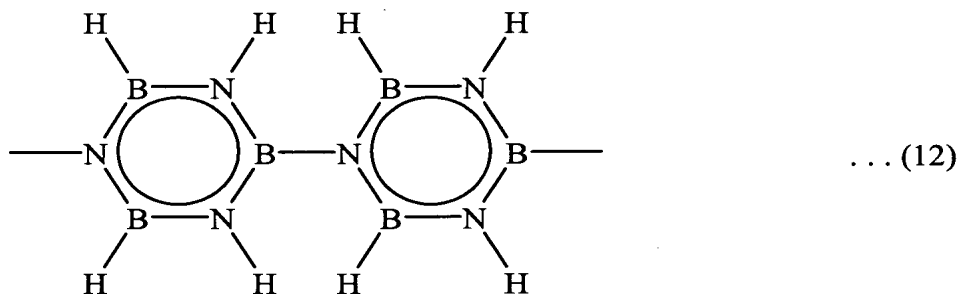
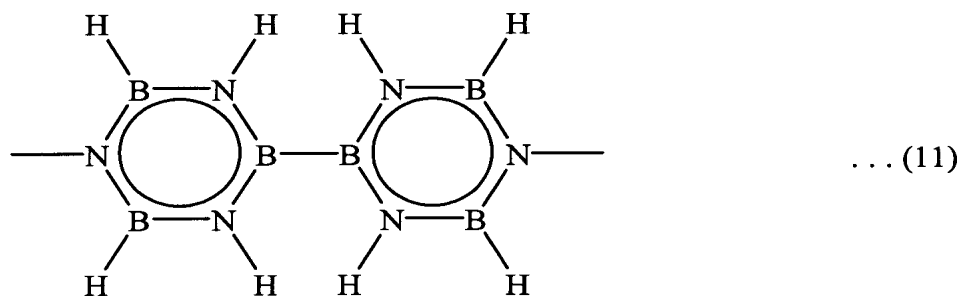
Claim 1 (Previously Presented): An insulation film for use between semiconductor layers, comprising borazine moieties shown by the following formula (1), (2), or (3) as part of an inorganic or organic material molecule, wherein said film has a dielectric constant of at most 2.4 and a thermal resistance of at least 450°C.

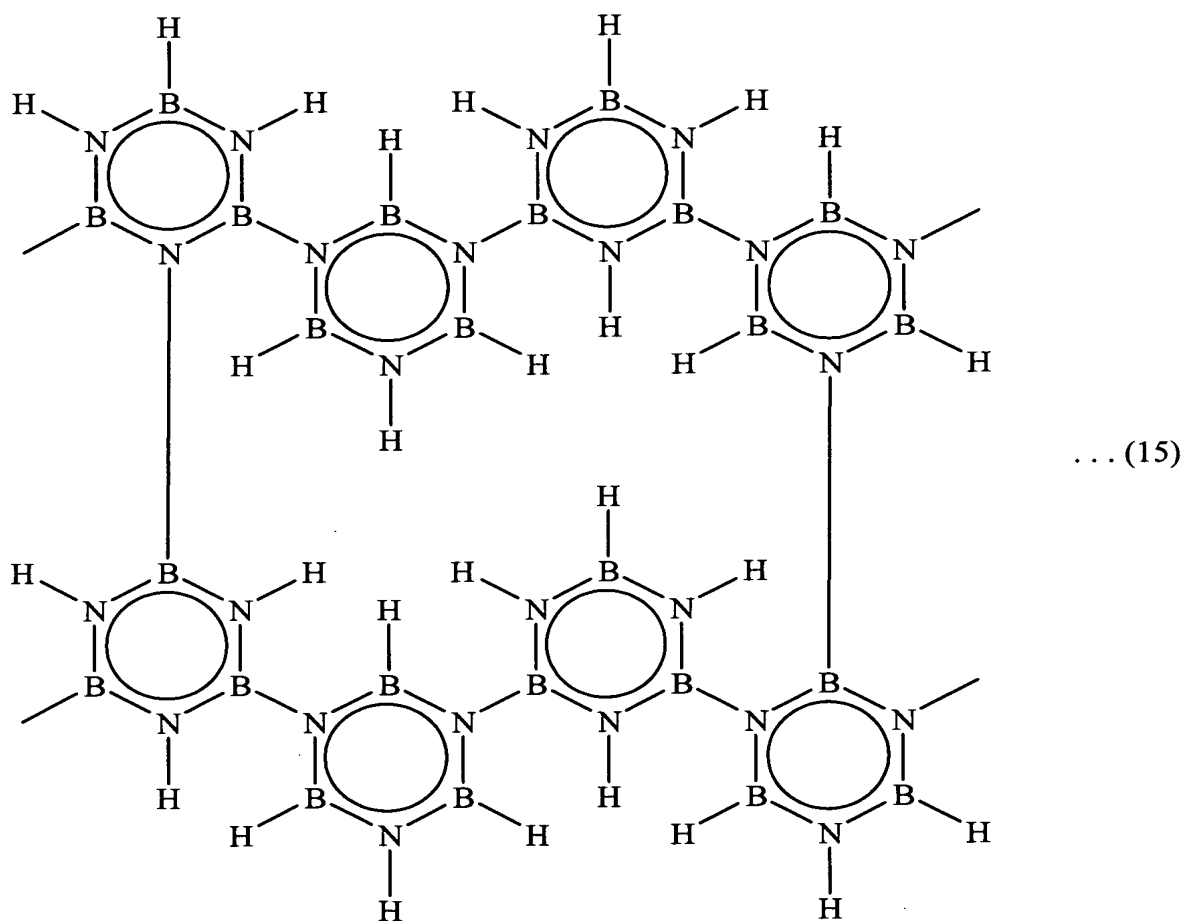
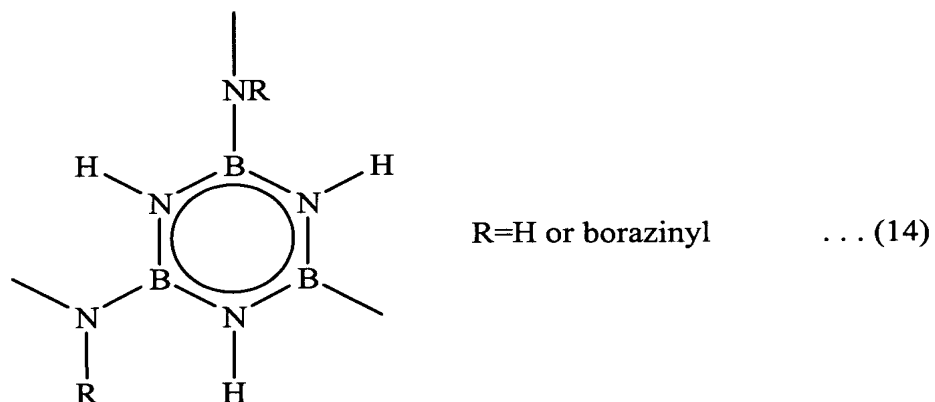


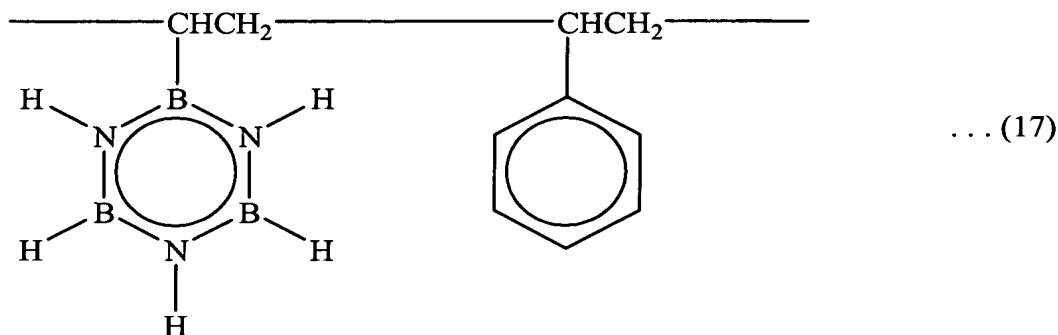
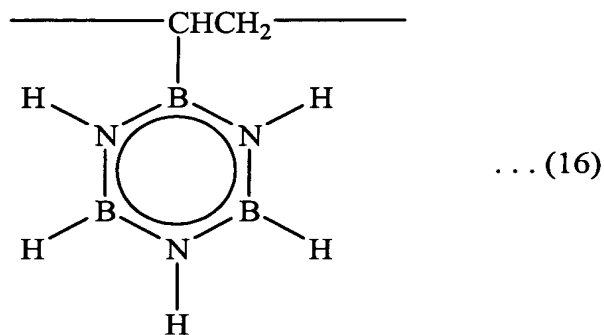
Claim 2 (Canceled).

Claim 3 (Previously Presented): A semiconductor device, comprising the insulation film of Claim 1, between semiconductor layers.

Claim 4 (Previously Presented): The insulation film of Claim 1, wherein said molecule contains at least one moiety selected from the following formulae (11) – (17):

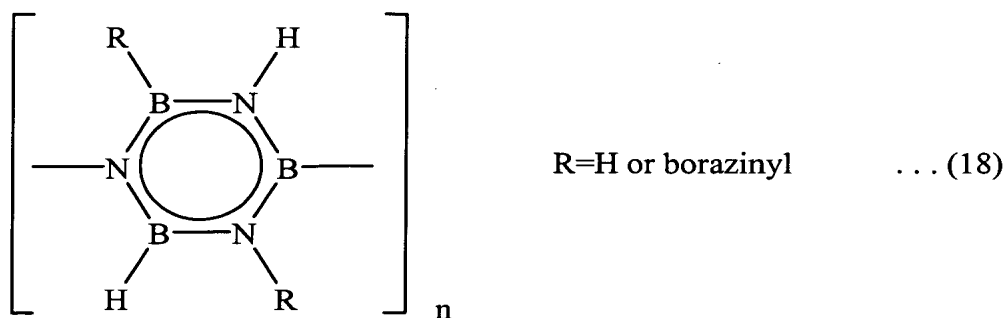






Claim 5 (Previously Presented) The insulation film material of Claim 1, wherein the inorganic material is selected from the group consisting of silicates, silazanes, silsequioxanes, siloxanes, and silanes, and the organic material is selected from the group consisting of poly(aryl ether), parylene, polyphenylene, polyphenylenevinylene, and polybenzocyclobutene.

Claim 6 (Previously Presented): A film comprising a material having the following formula (18):



wherein n is an integer, and having a gold electrode deposited thereon, wherein said material may be partially crosslinked.

Claim 7 (Previously Presented): A film comprising poly(aminoborazinyl) having a gold electrode deposited thereon, wherein the poly(aminoborazinyl) is partially crosslinked.

Claim 8 (Previously Presented): A film comprising poly(B-vinylborazine), and having a gold electrode deposited thereon, wherein the poly(B-vinylborazine) is partially crosslinked.

Claim 9 (Previously Presented): A film comprising a poly(styrene-co-B-vinylborazine), and having a gold electrode deposited thereon, wherein the poly(styrene-co-B-vinylborazine) is partially crosslinked.

Claim 10 (Canceled).

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Reply to Final Office Action dated November 19, 2004

DISCUSSION OF THE AMENDMENT

Claim 10 has been canceled.

Claims 1 and 3-9 are now pending in the application.